











LM6152, LM6154

SNOS752E -MAY 1999-REVISED SEPTEMBER 2014

LM6152/LM6154 Dual and Quad 75 MHz GBW Rail-to-Rail I/O Operational Amplifiers

Features

- At $V_S = 5V$, typical unless noted.
- Greater than Rail-to-rail Input CMVR -0.2 5V to 5.25 V
- Rail-to-rail Output Swing 0.01 V to 4.99 V
- Wide Gain-bandwidth 75 MHz @ 100 kHz
- Slew Rate
 - Small Signal 5 V/µs
 - Large Signal 45 V/µs
- Low Supply Current 1.4 mA/amplifier
- Wide Supply Range 2.7 V to 24 V
- Fast Settling Time of 1.1 µs for 2 V Step (to 0.01%)
- PSRR 91 dB
- CMRR 84 dB

Applications

- Portable High Speed Instrumentation
- Signal Conditioning Amplifier/ADC Buffers
- **Barcode Scanners**

3 Description

patented circuit topologies, LM6152/LM6154 provides new levels of speed vs. power performance in applications where low voltage supplies or power limitations previously made compromise necessary. With only 1.4 mA/amplifier supply current, the 75 MHz gain bandwidth of this device supports new portable applications where higher power devices unacceptably drain battery life. The slew rate of the devices increases with increasing input differential voltage, thus allowing the device to handle capacitive loads while maintaining large signal amplitude.

The LM6152/LM6154 can be driven by voltages that exceed both power supply rails, thus eliminating concerns about exceeding the common-mode voltage range. The rail-to-rail output swing capability provides the maximum possible dynamic range at the output. This is particularly important when operating on low supply voltages.

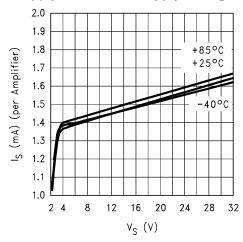
Operating on supplies from 2.7 V to over 24 V, the LM6152/LM6154 is excellent for a very wide range of applications, from battery operated systems with large bandwidth requirements to high speed instrumentation.

Device Information⁽¹⁾

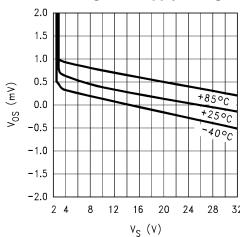
PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM6152	SOIC (8)	4.902 mm × 3.912 mm
LM6154	SOIC (14)	8.636 mm × 3.912 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Supply Current vs. Supply Voltage



Offset Voltage vs. Supply voltage





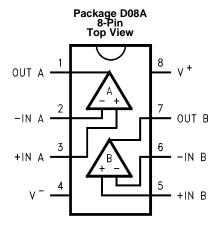
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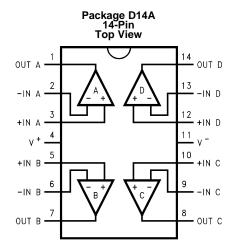
4 Revision History

Changes from Revision D (March 2013) to Revision E	Page
 Changed "Junction Temperature Range" to "Operating Temperature Range" and deleted "T_J" in Recommended Operating Conditions 	4
Deleted T _J = 25°C for Electrical Characteristics Tables	
Changes from Revision C (March 2013) to Revision D	Page
Changed layout of National Data Sheet to TI format	15



5 Pin Configuration and Functions





Pin Functions

	PIN			
NAME	LM6152	LM6154	1/0	DESCRIPTION
NAME	D08A	D14A		
-IN A	2	2	I	ChA Inverting Input
+IN A	3	3	I	ChA Non-inverting Input
-IN B	6	6	1	ChB Inverting Input
+IN B	5	5	I	ChB Non-inverting Input
-IN C		9	I	ChC Inverting Input
+IN C		10	I	ChC Non-inverting Input
-IN D		13	1	ChD Inverting Input
+IN D		12	1	ChD Non-inverting Input
OUT A	1	1	0	ChA Output
OUT B	7	7	0	ChB Output
OUT C		8	0	ChC Output
OUT D		14	0	ChD Output
V-	4	11	I	Negative Supply
V ⁺	8	4	I	Positive Supply



6 Specifications

6.1 Absolute Maximum Ratings (1)(2)

	MIN	MAX	UNIT
Differential Input Voltage		±15	٧
Voltage at Input/Output Pin		(V ⁺) + 0.3 (V ⁻) -0.3	٧
Supply Voltage (V ⁺ - V ⁻)		35	٧
Current at Input Pin		±10	mA
Current at Output Pin (3)		±25	mA
Current at Power Supply Pin		50	mA
Lead Temperature (soldering, 10 sec)		260	°C
Junction Temperature (4)		150	ů

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C.
- (4) The maximum power dissipation is a function of T_{J(MAX)}, R_{BJA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)}-T_A)/R_{BJA}. All numbers apply for packages soldered directly into a PC board.

6.2 Handling Ratings

			MIN	MAX	UNIT
T _{stg}	Storage temperature rang	e	-65	+150	°C
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾		2500	V

JEDEC document JEP155 states that 2500-V HBM allows safe manufacturing with a standard ESD control process. Human body model is 1.5 kΩ in series with 100 pF

6.3 Recommended Operating Conditions⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

, , ,			
	MIN	MAX	UNIT
Supply Voltage	2.7	≤ V ⁺ ≤ 24	V
Operating Temperature Range, LM6152,LM6154	0	+70	°C

⁽¹⁾ Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾	D08A	D14A	LINUT
I HERMAL METRIC**/		14 PINS	UNIT
R _{0JA} Junction-to-ambient thermal resistance	193°C/W	126°C/W	°C/W

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.



6.5 5.0 V DC Electrical Characteristics

Unless otherwise specified, all limits are ensured for $V^+ = 5.0V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extremes.

	PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	LM6152AC LIMIT ⁽²⁾	LM6154BC LM6152BC LIMIT ⁽²⁾	UNIT
V _{OS}	Input Offset Voltage		0.54	2 4	5 7	mV max
TCV _{OS}	Input Offset Voltage Average Drift		10			μV/°C
I _B	Input Bias Current	0V ≤ V _{CM} ≤ 5V	500 750	980 1500	980 1500	nA max
I _{OS}	Input Offset Current		32 40	100 160	100 160	nA max
R _{IN}	Input Resistance, CM	0V ≤ V _{CM} ≤ 4V	30			ΜΩ
CMRR	Common Mode Rejection Ratio	0V ≤ V _{CM} ≤ 4V	94	70	70	dB
		$0V \le V_{CM} \le 5V$	84	60	60	min
PSRR	Power Supply Rejection Ratio	5V ≤ V ⁺ ≤ 24V	91	80	80	dB min
V _{CM}	Input Common-Mode Voltage Range	Low	-0.25	0	0	V
		High	5.25	5.0	5.0	V
A _V	Large Signal Voltage Gain	$R_L = 10 \text{ k}\Omega$	214	50	50	V/mV min
Vo	Output Swing	$R_L = 100 \text{ k}\Omega$	0.006	0.02 0.03	0.02 0.03	V max
			4.992	4.97 4.96	4.97 4.96	V min
		$R_L = 2 k\Omega$	0.04	0.10 0.12	0.10 0.12	V max
			4.89	4.80 4.70	4.80 4.70	V min
I _{SC}	Output Short Circuit Current	Sourcing	0.0	3 2.5	3 2.5	mA min
			6.2	27 17	27 17	mA max
		Sinking	46.0	7 5	7 5	mA min
			16.9	40	40	mA max
Is	Supply Current	Per Amplifier	1.4	2 2.25	2 2.25	mA max

Typical Values represent the most likely parametric norm. All limits are specified by testing or statistical analysis.



6.6 5.0 V AC Electrical Characteristics

Unless otherwise specified, all limits ensured for V⁺ = 5.0V, V⁻ = 0V, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to V⁺/2. **Boldface** limits apply at the temperature extremes.

	PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	LM6152AC LIMIT ⁽²⁾	LM6154BC LM6152BC LIMIT ⁽²⁾	UNIT
SR	Slew Rate	$\pm 4V$ Step @ $V_S = \pm 6V$, $R_S < 1 k\Omega$	30	24 15	24 15	V/µs min
GBW	Gain-Bandwidth Product	f = 100 kHz	75			MHz
	Amp-to-Amp Isolation	$R_L = 10 \text{ k}\Omega$	125			dB
e _n	Input-Referred Voltage Noise	f = 1 kHz	9			nV/√ Hz
i _n	Input-Referred Current Noise	f = 1 kHz	0.34			pA/√ Hz
T.H.D	Total Harmonic Distortion	f = 100 kHz, R _L = 10 kΩ A _V = -1, V _O = 2.5 V _{PP}	-65			dBc
ts	Settling Time	2V Step to 0.01%	1.1			μs

Typical Values represent the most likely parametric norm. All limits are specified by testing or statistical analysis.

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6.7 2.7 V DC Electrical Characteristics

Unless otherwise specified, all limits are ensured for $V^+ = 2.7V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extremes.

	PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	LM6152AC LIMIT ⁽²⁾	LM6154BC LM6152BC LIMIT ⁽²⁾	UNIT
Vos	Input Offset Voltage		0.8	2 5	5 8	mV max
TCV _{OS}	Input Offset Voltage Average Drift		10			μV/°C
I_B	Input Bias Current		500			nA
Ios	Input Offset Current		50			nA
R_{IN}	Input Resistance, CM	$0V \le V_{CM} \le 1.8V$	30			ΜΩ
CMRR	Common Mode Rejection Ratio	$0V \le V_{CM} \le 1.8V$	88			dB
		$0V \le V_{CM} \le 2.7V$	78			
PSRR	Power Supply Rejection Ratio	$3V \le V^+ \le 5V$	69			dB
V_{CM}	Input Common-Mode Voltage Range	Low	-0.25	0	0	V
		High	2.95	2.7	2.7	V
A_V	Large Signal Voltage Gain	$R_L = 10 \text{ k}\Omega$	5.5			V/mV
Vo	Output Swing	$R_L = 10 \text{ k}\Omega$	0.032	0.07 0.11	0.07 0.11	V max
			2.68	2.64 2.62	2.64 2.62	V min
I _S	Supply Current	Per Amplifier	1.35			mA

⁽¹⁾ Typical Values represent the most likely parametric norm.

6.8 2.7 V AC Electrical Characteristics

Unless otherwise specified, all limits are ensured for $V^+ = 2.7V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extremes.

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	LM6152AC LIMIT ⁽²⁾	LM6154BC LM6152BC LIMIT ⁽²⁾	UNIT
GBW	Gain-Bandwidth Product	f = 100 kHz	80			MHz

⁽¹⁾ Typical Values represent the most likely parametric norm.

⁽²⁾ All limits are specified by testing or statistical analysis.

⁽²⁾ All limits are specified by testing or statistical analysis.



6.9 24 V DC Electrical Characteristics

Unless otherwise specified, all limits are ensured for $V^+ = 24V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extremes.

	PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	LM6152AC LIMIT ⁽²⁾	LM6154BC LM6152BC LIMIT ⁽²⁾	UNIT
V _{OS}	Input Offset Voltage		0.3	2 4	7 9	mV max
TCV _{OS}	Input Offset Voltage Average Drift		10			μV/°C
I _B	Input Bias Current		500			nA
Ios	Input Offset Current		32			nA
R _{IN}	Input Resistance, CM	$0V \le V_{CM} \le 23V$	60			$\text{Meg }\Omega$
CMRR Co	Common Mode Rejection Ratio	0V ≤ V _{CM} ≤ 23V	94			dB
		$0V \le V_{CM} \le 24V$	84			UD
PSRR	Power Supply Rejection Ratio	$0V \le V_{CM} \le 24V$	95			dB
V _{CM}	Input Common-Mode Voltage Range	Low	-0.25	0	0	V
		High	24.25	24	24	V
A _V	Large Signal Voltage Gain	$R_L = 10 \text{ k}\Omega$	55			V/mV
Vo	Output Swing	$R_L = 10 \text{ k}\Omega$	0.044	0.075 0.090	0.075 0.090	V max
			23.91	23.8 23.7	23.8 23.7	V min
Is	Supply Current	Per Amplifier	1.6	2.25 2.50	2.25 2.50	mA max

⁽¹⁾ Typical Values represent the most likely parametric norm.

6.10 24 V AC Electrical Characteristics

Unless otherwise specified, all limits are ensured for $V^+ = 24V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extremes.

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	LM6152AC LIMIT ⁽²⁾	LM6154BC LM6152BC LIMIT ⁽²⁾	UNIT
GBW	Gain-Bandwidth Product	f = 100 kHz	80			MHz

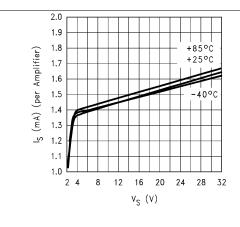
⁽¹⁾ Typical Values represent the most likely parametric norm.

⁽²⁾ All limits are specified by testing or statistical analysis.

⁽²⁾ All limits are specified by testing or statistical analysis.



6.11 Typical Performance Characteristics



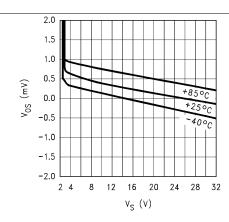
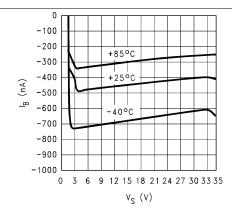


Figure 1. Supply Current vs. Supply Voltage





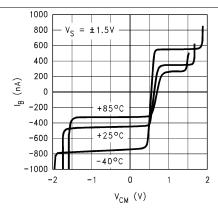
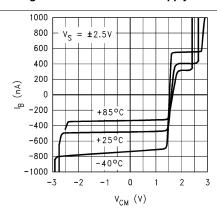


Figure 3. Bias Current vs. Supply voltage





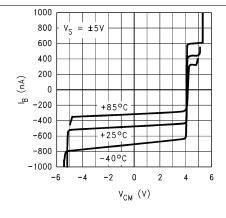


Figure 5. Bias Current vs. V_{CM}

Figure 6. Bias Current vs. V_{CM}

STRUMENTS

Typical Performance Characteristics (continued)

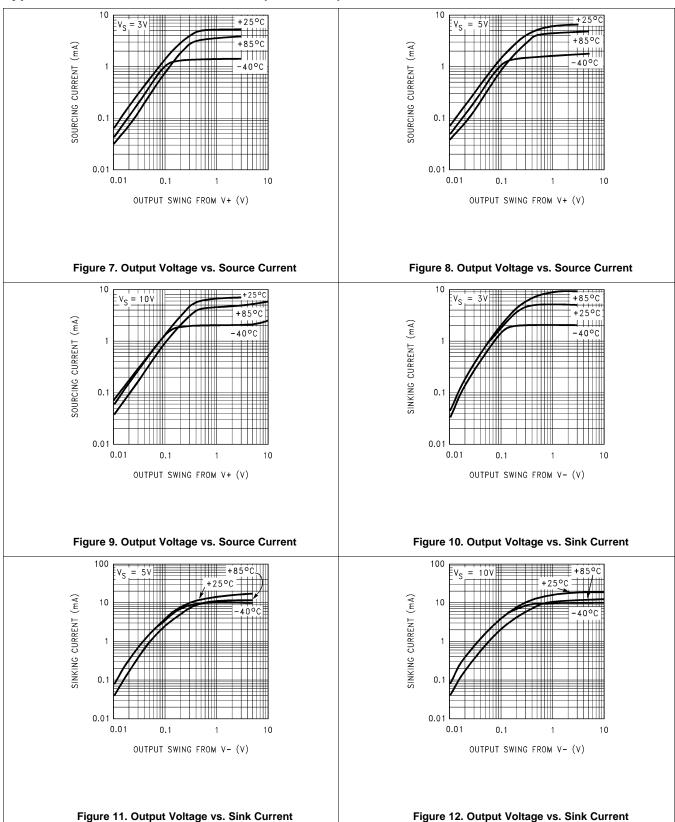
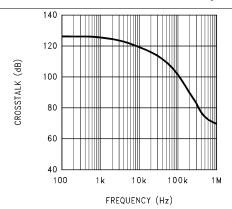


Figure 11. Output Voltage vs. Sink Current

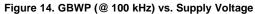


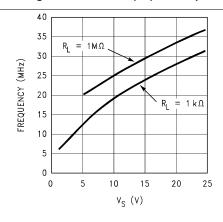
Typical Performance Characteristics (continued)



60 50 40 40 30 R_L = 1 kΩ 10 0 5 10 15 20 25 V_S (V)

Figure 13. Crosstalk (dB) vs. Frequency





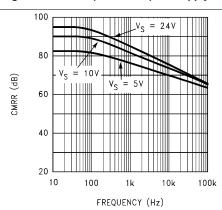
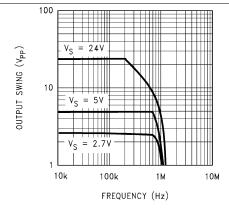


Figure 15. Unity Gain Frequency vs. Supply Voltage for Various Loads





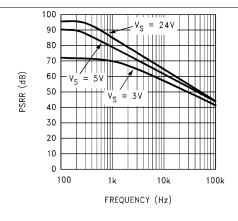


Figure 17. Voltage Swing vs. Frequency $(C_L = 100 pF)$

Figure 18. PSRR vs. Frequency

TEXAS INSTRUMENTS

Typical Performance Characteristics (continued)

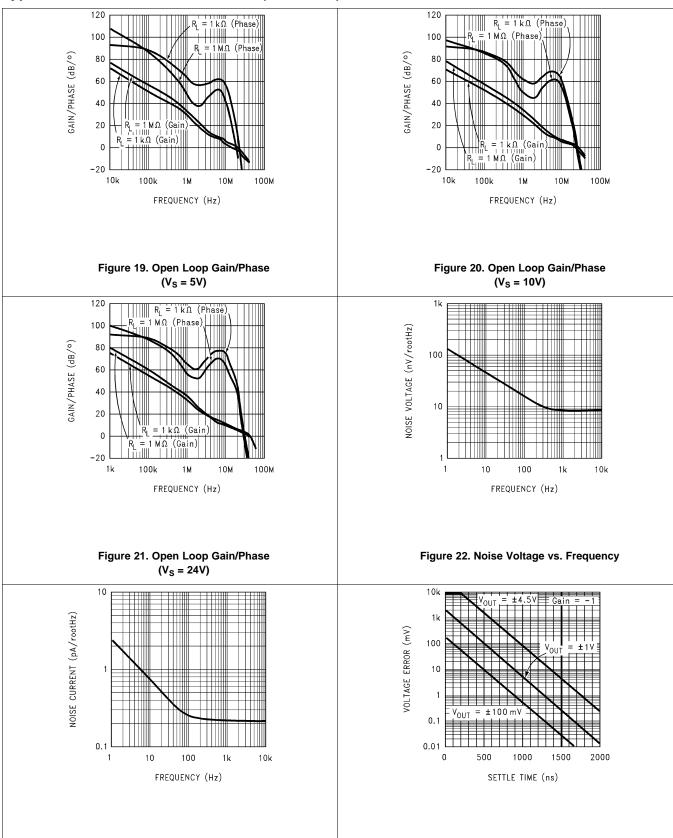
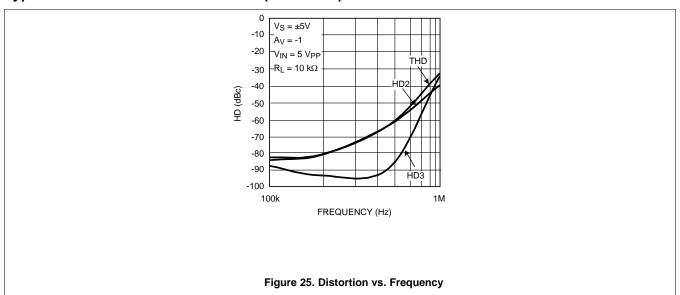


Figure 23. Noise Current vs. Frequency

Figure 24. Voltage Error vs. Settle Time



Typical Performance Characteristics (continued)





7 Application and Implementation

The LM6152/LM6154 is ideally suited for operation with about 10 k Ω (Feedback Resistor, R_F) between the output and the negative input terminal.

With R_F set to this value, for most applications requiring a close loop gain of 10 or less, an additional small compensation capacitor (C_F) (see Figure 26) is recommended across R_F in order to achieve a reasonable overshoot (10%) at the output by compensating for stray capacitance across the inputs.

The optimum value for C_F can best be established experimentally with a trimmer cap in place since its value is dependant on the supply voltage, output driving load, and the operating gain. Below, some typical values used in an inverting configuration and driving a 10 k Ω load have been tabulated for reference:

V_S Volts C_F pF BW (-3 dB) **GAIN** MHz -1 4 5.6 3 -10 6.8 1.97 0.797 -100 None -1 2.2 6.6 -10 4.7 2.2 24 -100 None 0.962

Table 1. Typical BW (-3 dB) at Various Supply Voltage and Gains

In the non-inverting configuration, the LM6152/LM6154 can be used for closed loop gains of +2 and above. In this case, also, the compensation capacitor (C_F) is recommended across R_F (= 10 k Ω) for gains of 10 or less.

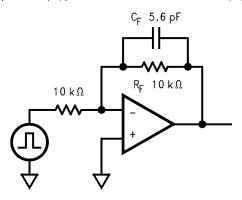


Figure 26. Typical Inverting Gain Circuit $A_V = -1$

Because of the unique structure of this amplifier, when used at low closed loop gains, the realizable BW will be much less than the GBW product would suggest.

The LM6152/LM6154 brings a new level of ease of use to op amp system design.

The greater than rail-to-rail input voltage range eliminates concern over exceeding the common-mode voltage range. The rail-to-rail output swing provides the maximum possible dynamic range at the output. This is particularly important when operating on low supply voltages.

The high gain-bandwidth with low supply current opens new battery powered applications where higher power consumption previously reduced battery life to unacceptable levels.

The ability to drive large capacitive loads without oscillating functional removes this common problem.

To take advantage of these features, some ideas should be kept in mind.

The LM6152/LM6154, capacitive loads do not lead to oscillations, in all but the most extreme conditions, but they will result in reduced bandwidth. They also cause increased settling time.



Unlike most bipolar op amps, the unique phase reversal prevention/speed-up circuit in the input stage, causes the slew rate to be very much a function of the input pulse amplitude. This results in a 10 to 1 increase in slew rate when the differential input signal increases. Large fast pulses will raise the slew-rate to more than 30 V/µs.

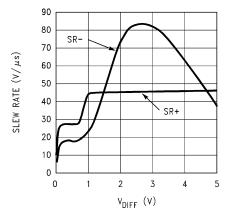


Figure 27. Slew Rate vs. VDIFF

The speed-up action adds stability to the system when driving large capacitive loads.

A conventional op amp exhibits a fixed maximum slew-rate even though the differential input voltage rises due to the lagging output voltage. In the LM6152/LM6154, increasing lag causes the differential input voltage to increase but as it does, the increased slew-rate keeps the output following the input much better. This effectively reduces phase lag. As a result, the LM6152/LM6154 can drive capacitive loads as large as 470 pF at gain of 2 and above, and not oscillate.

Capacitive loads decrease the phase margin of all op amps. This can lead to overshoot, ringing and oscillation. This is caused by the output resistance of the amplifier and the load capacitance forming an R-C phase shift network. The LM6152/6154 senses this phase shift and partly compensates for this effect.



8 Device and Documentation Support

8.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY	
LM6152	Click here	Click here	Click here	Click here	Click here	
LM6154	Click here	Click here	Click here	Click here	Click here	

8.2 Trademarks

All trademarks are the property of their respective owners.

8.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

8.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

www.ti.com

10-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
LM6152ACM/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52ACM
LM6152ACM/NOPB.A	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52ACM
LM6152ACM/NOPB.B	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52ACM
LM6152ACMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52ACM
LM6152ACMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52ACM
LM6152ACMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52ACM
LM6152BCM/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52BCM
LM6152BCM/NOPB.A	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52BCM
LM6152BCM/NOPB.B	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52BCM
LM6152BCMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52BCM
LM6152BCMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52BCM
LM6152BCMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM61 52BCM
LM6154BCM/NOPB	Active	Production	SOIC (D) 14	55 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM6154BCM
LM6154BCM/NOPB.A	Active	Production	SOIC (D) 14	55 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM6154BCM
LM6154BCM/NOPB.B	Active	Production	SOIC (D) 14	55 TUBE	-	Call TI	Call TI	0 to 70	
LM6154BCMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM6154BCM
LM6154BCMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM6154BCM
LM6154BCMX/NOPB.B	Active	Production	SOIC (D) 14	2500 LARGE T&R	-	Call TI	Call TI	0 to 70	

⁽¹⁾ Status: For more details on status, see our product life cycle.



PACKAGE OPTION ADDENDUM

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- (2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM6152ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM6152BCMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM6154BCMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type		Length (mm)	Width (mm)	Height (mm)		
LM6152ACMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM6152BCMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM6154BCMX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

All difficultions are norminal								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LM6152ACM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM6152ACM/NOPB.A	D	SOIC	8	95	495	8	4064	3.05
LM6152ACM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM6152BCM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM6152BCM/NOPB.A	D	SOIC	8	95	495	8	4064	3.05
LM6152BCM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM6154BCM/NOPB	D	SOIC	14	55	495	8	4064	3.05
LM6154BCM/NOPB.A	D	SOIC	14	55	495	8	4064	3.05





NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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